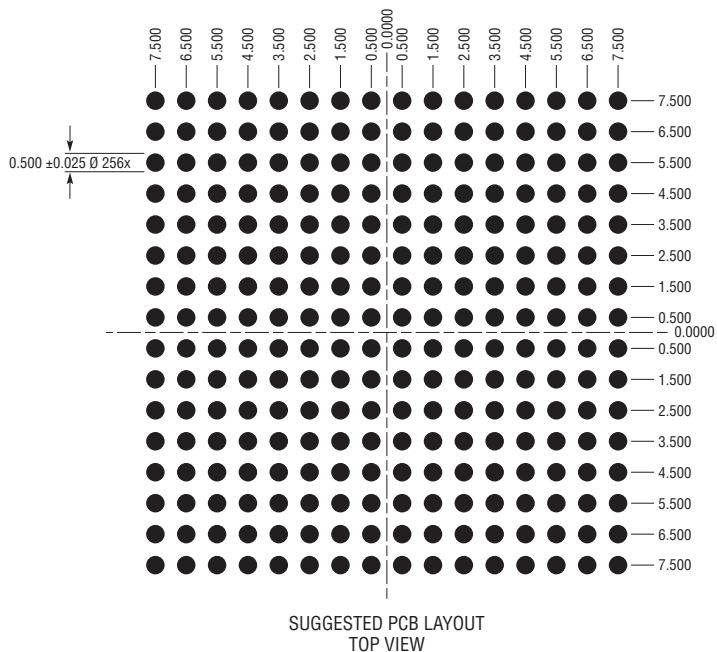
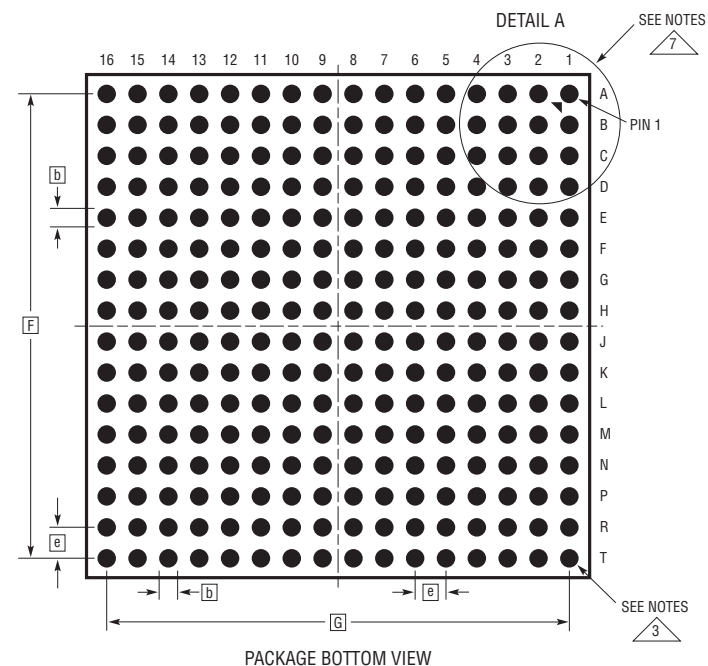
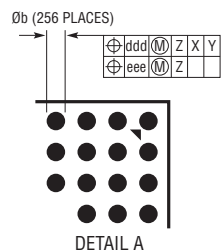
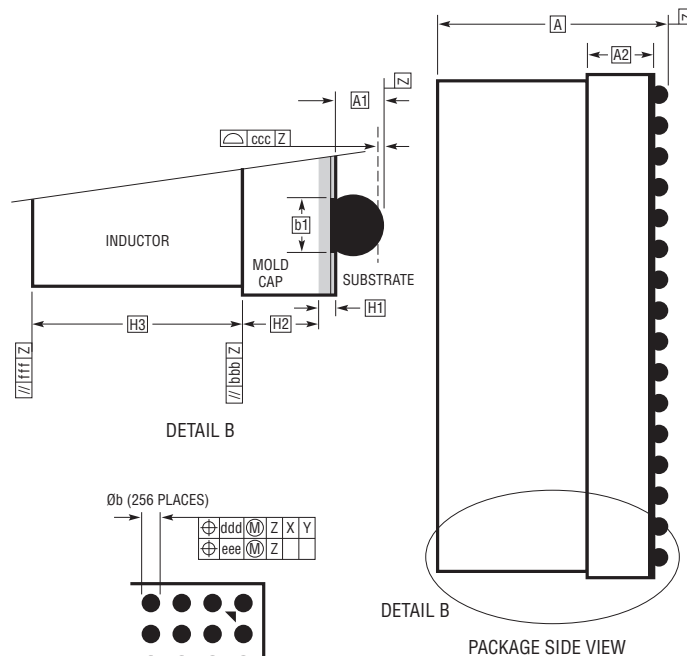
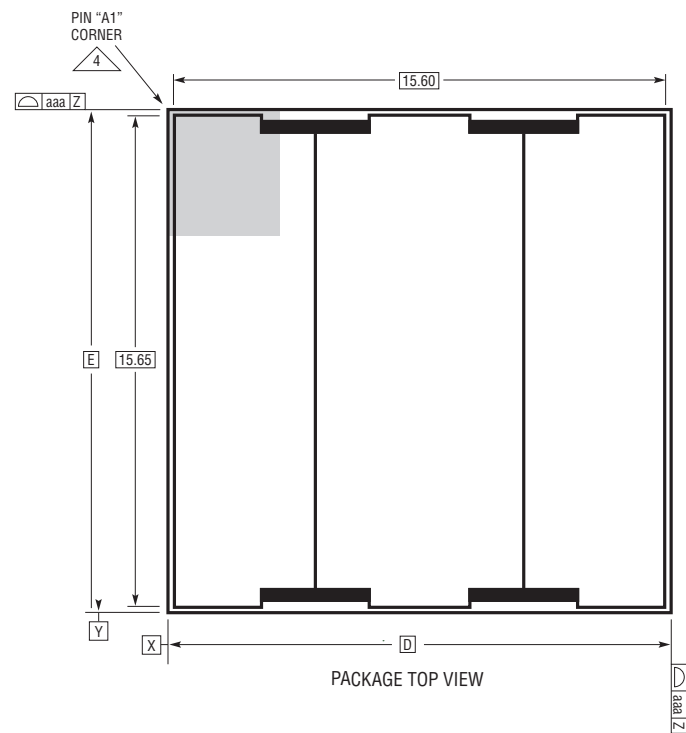


BGA Package
256-Lead (16mm × 16mm × 7.72mm)
 (Reference LTC DWG # 05-08-1567 Rev A)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	7.41	7.72	8.03	
A1	0.45	0.50	0.55	BALL HT
A2	1.73	1.82	1.91	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D		16.00		
E		16.00		
e		1.00		
F		15.00		
G		15.00		
H1	0.28	0.32	0.36	SUBSTRATE THK
H2	1.45	1.50	1.55	MOLD CAP HT
H3	5.28	5.40	5.52	INDUCTOR HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	
fff			0.35	

TOTAL NUMBER OF BALLS: 256

- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 - ALL DIMENSIONS ARE IN MILLIMETERS
 - BALL DESIGNATION PER JESD MS-028 AND JEP95
 - DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 - PRIMARY DATUM -Z- IS SEATING PLANE
 - SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
 - PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μ Module PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

